

ABSTRACT OF DISCLOSURE

A process for fabricating an integrated circuit package includes: providing a substrate having conductive traces therein, the substrate including a cavity therein; mounting a semiconductor die to a first surface of the substrate, in a flip-chip orientation such that a sensor portion of the semiconductor die is aligned with the cavity and conductive interconnects connect pads of the semiconductor die to the conductive traces of the substrate; filling an area surrounding the interconnects with an underfill material; and mounting a plurality of conductive balls on the first surface of the substrate and in electrical connection with the conductive traces such that ones of the conductive balls are connected to ones of the pads of the semiconductor die via the conductive traces.